

REMARKS

INTRODUCTION

In accordance with the foregoing, claims 5, 10 and 11 have been amended. Claims 6-9 and 16-21 have been cancelled. Claims 1-5 and 10-15 are pending and under consideration.

CLAIM REJECTIONS

Claims 1-6, 12 and 14-21 were rejected under 35 USC 103(a) as being unpatentable over Ito et al. (US 6,410,904) (hereinafter “Ito”) in view of the applicant’s admitted prior art (hereinafter “AAPA”).

Claims 7-11 and 13 were rejected under 35 USC 103(a) as being unpatentable over Ito in view of the AAPA and further in view of Chun et al. (US 6,525,405) (hereinafter “Chun”).

Claim 1

Claim 1 recites: “...a plurality of lands provided on the main board, electrically connected to the second leads...” In the Office Action, the Examiner notes that this feature is not discussed in Ito and instead relies on the AAPA to show the plurality of lands electrically connected to the second leads. However, the AAPA does not discuss a plurality of lands electrically connected to seconds. By contrast, the AAPA specifically discusses in paragraph [0008] that “The leads 4 of the laser diode module 3 are electrically connected to the **leads** 14 of the drive chip 13 **indirectly** by a wiring provided on the main board 11 [emphasis added].” As the feature of claim 1 where a plurality of lands is provided on the main board to electrically connect to the second leads is not discussed in either Ito or the AAPA, it is respectfully submitted that claim 1 patentably distinguishes over the relied upon prior art.

This technical feature of claim 1 where the main board has the lands electrically connected to the second leads, and a through hole through which the laser diode module main body 21 passes, provides that in a state in which the laser diode module main body is coupled to the rear surface of the drive chip, the main board is directly coupled to the rear surface of the drive chip so that the structure may be made compact. Further, since part of the laser diode module main body protrudes through the through hole provided at the main board, mechanical interference and optical interference can be avoided.

Withdrawal of the foregoing rejection is requested.

Claims 2-4

Claim 2 recites: "...a plurality of lands provided on the main board, electrically connected to the second leads..." In accordance with the foregoing, it is respectfully submitted that the feature of claim 2 where a plurality of lands is provided on the main board to electrically connect to the second leads is not discussed in either Ito or the AAPA.

Claim 2 further recites: "...a bobbin connected to the base through a suspension...an objective lens mounted on the bobbin...a magnetic actuating unit provided across the base...a photodetector..." In accordance with MPEP 2144.03 the reliance on Official Notice to disclose the foregoing features of claim 2 is hereby traversed. In further accordance with MPEP 2144.03, the traversal of the use of Official Notice is made on the grounds that it would not be appropriate for the Examiner to take official notice of facts without citing a prior art reference where the facts asserted to be well known are not capable of instant and unquestionable demonstration as being well-known.

Claims 3 and 4 depend on claim 2 and are therefore believed to be allowable for at least the foregoing reasons.

Withdrawal of the foregoing rejection is requested.

Claims 5-15

Amended claim 5 recites: "...the drive chip is packaged with a mold resin in a state in which a semiconductor device is mounted on a lead frame, a plurality of coupling holes being formed in the mold resin of the drive chip, wherein the plurality of laser diode leads are respectively inserted into the coupling holes and a plurality of inner connectors are formed in each of the coupling holes, respectively, to which each of the laser diode leads are respectively electrically connected." Support for this amendment may be found in at least original claims 6-9. In the Office Action, the Examiner relies on Ito to supply the feature of claim 5 where a plurality of inner connectors are formed in each of the coupling holes. However, in contrast to claim 5, Ito discusses that: "As shown in FIGS. 4 and 6, the pins 68a, 68b, 68c of the semiconductor laser device 6 pass through from the solder side 5a to the component side 5b and are electrically

connected to the drive circuit 5 by soldering." See Ito, 8:25-8:29 and Figures 4 and 6. This section of Ito, nor any other, discusses the inner connectors recited in claim 5.

This technical feature of claim 5 provides that in a state in which the laser diode module main body is coupled to the rear surface of the drive chip, the main board is directly coupled to the rear surface of the drive chip so that the structure may be made compact. Further, since part of the laser diode module main body protrudes through the through hole provided at the main board, mechanical interference and optical interference can be avoided.

Claims 6-9 have been cancelled. Claims 10-15 depend on claim 5 and are therefore believed to be allowable for at least the foregoing reasons.

Withdrawal of the foregoing rejection is requested.

Claims 16-21

Claims 16-21 have been cancelled.

CONCLUSION

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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